

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Tomohiro OKUMURA et al.

Serial No. NEW

Filed February 23, 2000

PLASMA PROCESSING METHOD AND
APPARATUS

Attn: APPLICATION BRANCH

Docket No. 00177/530809

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Please amend the above-identified application as follows.

In the Claims:

Kindly amend claim 18 as follows.

Claim 18, line 2, delete "or 15".

Kindly add new claim 55 as follows.

55. A plasma processing apparatus according to Claim 15, wherein the plasma has a groove depth of not less than 5 mm.